

# Polish Cut System CSX-100 lab

Ultrasonic Cutting System for Cross-Section Observation



## Polish Cut™ effect

1. Combines cutting and polishing into a single process.
2. Reduces labor and time spent on performing cross-section observation work.



Bump



Cell Phone Lens



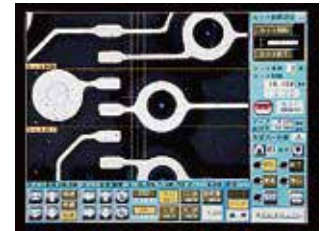
Bonding Wire

# Polish Cut System

Shorten cutting time of test pieces for cross-section observation!!

## Features

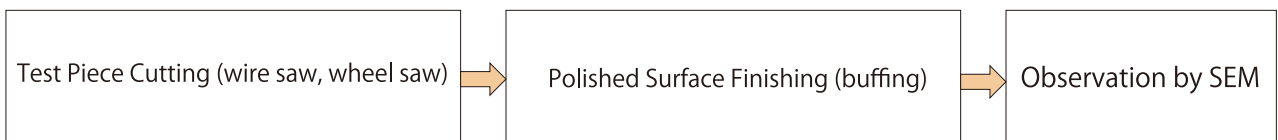
- ◆ Polish cut for hard-to-cut materials such as SiC, Ceramics(LTCC) or composite materials
- ◆ Long-life blade
- ◆ Cutting blade extends 10mm
- ◆ Easy alignment to cutting line
- ◆ Easy fixing of workpieces using cutting tape
- ◆ CSX-100 is suitable for small scale production as well



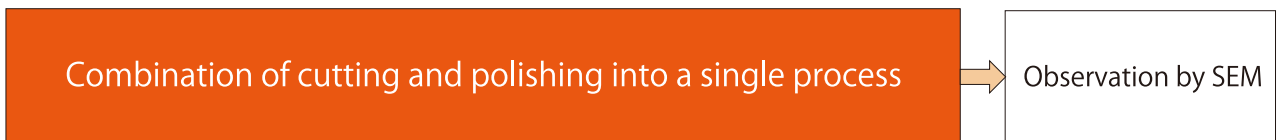
CSX-100 Operation Screen

## Comparison between Previous method and Ultrasonic Cutting

Previous Method



Ultrasonic Wave Cutting



## Specifications



Model	CSX-100 Lab
Work Size	100φ (75 squares)
Work Height	9mm
Operation/Display	Touch panel
Utilities	3 phase 200V 30A, water, compressed air, drain, exhaust
Dimensions	650 <sup>(W)</sup> × 905 <sup>(D)</sup> × 1,350 <sup>(H)</sup>
Weight	350 kg

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